

TPCP8206

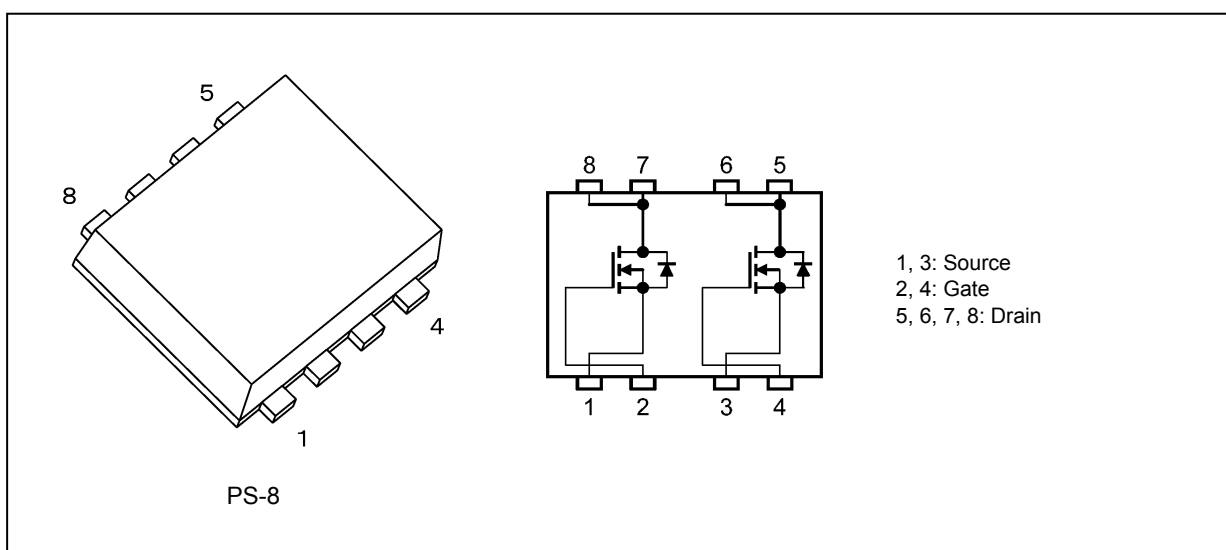
1. Applications

- Mobile Equipments

2. Features

- (1) Small footprint due to a small and thin package
- (2) Low drain-source on-resistance: $R_{DS(ON)} = 19 \text{ m}\Omega$ (typ.) ($V_{GS} = 4.5 \text{ V}$)
- (3) Low leakage current: $I_{DSS} = 10 \text{ }\mu\text{A}$ (max) ($V_{DS} = 20 \text{ V}$)
- (4) Enhancement mode: $V_{th} = 0.5$ to 1.2 V ($V_{DS} = 10 \text{ V}$, $I_D = 0.2 \text{ mA}$)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	20	V
Gate-source voltage	V_{GSS}	± 12	
Drain current (DC) (Note 1)	I_D	6.0	A
Drain current (pulsed) (Note 1)	I_{DP}	20	
Power dissipation (single operation) (t = 5 s) (Note 2), (Note 4)	$P_{D(1)}$	1.48	W
Power dissipation (per device for dual operation) (t = 5 s) (Note 2), (Note 5)	$P_{D(2)}$	1.23	
Power dissipation (single operation) (t = 5 s) (Note 3), (Note 4)	$P_{D(1)}$	0.58	
Power dissipation (per device for dual operation) (t = 5 s) (Note 3), (Note 5)	$P_{D(2)}$	0.36	
Single-pulse avalanche energy (Note 6)	E_{AS}	23.4	mJ
Avalanche current	I_{AR}	6.0	A
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-ambient thermal resistance (single operation) (t = 5 s) (Note 2), (Note 4)	$R_{th(ch-a)(1)}$	84.4	°C/W
Channel-to-ambient thermal resistance (per device for dual operation) (t = 5 s) (Note 2), (Note 5)	$R_{th(ch-a)(2)}$	101.6	
Channel-to-ambient thermal resistance (single operation) (t = 5 s) (Note 3), (Note 4)	$R_{th(ch-a)(1)}$	215.5	
Channel-to-ambient thermal resistance (per device for dual operation) (t = 5 s) (Note 3), (Note 5)	$R_{th(ch-a)(2)}$	347.2	

Note 1: Ensure that the channel temperature does not exceed 150°C.

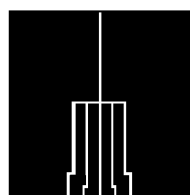
Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: Power dissipation and thermal resistance values per device with the other device being off (During single operation, power is supplied to only one of the two devices.)

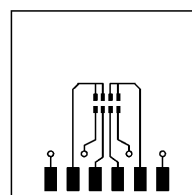
Note 5: Power dissipation and thermal resistance values per device for dual operation (During dual operation, power is evenly supplied to both devices.)

Note 6: $V_{DD} = 16\text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 0.5\text{ mH}$, $R_G = 1\ \Omega$, $I_{AR} = 6.0\text{ A}$



FR-4
25.4 × 25.4 × 0.8
(Unit: mm)

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)



FR-4
25.4 × 25.4 × 0.8
(Unit: mm)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 12\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 0.1	μA
Drain cut-off current	I_{DSS}	$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}$	—	—	10	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	20	—	—	V
	$V_{(BR)DSX}$	$I_D = 10\text{ mA}, V_{GS} = -12\text{ V}$	8	—	—	
Gate threshold voltage	V_{th}	$V_{DS} = 10\text{ V}, I_D = 0.2\text{ mA}$	0.5	—	1.2	
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS} = 2.5\text{ V}, I_D = 3.0\text{ A}$	—	27	35	$\text{m}\Omega$
		$V_{GS} = 4.5\text{ V}, I_D = 3.0\text{ A}$	—	19	24	

6.2. Dynamic Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	630	—	pF
Reverse transfer capacitance	C_{rss}		—	47	—	
Output capacitance	C_{oss}		—	144	—	
Switching time (rise time)	t_r	See Figure 6.2.1.	—	4.6	—	ns
Switching time (turn-on time)	t_{on}		—	11.8	—	
Switching time (fall time)	t_f		—	5.9	—	
Switching time (turn-off time)	t_{off}		—	23.3	—	

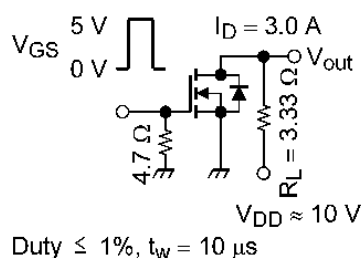


Fig. 6.2.1 Switching Time Test Circuit

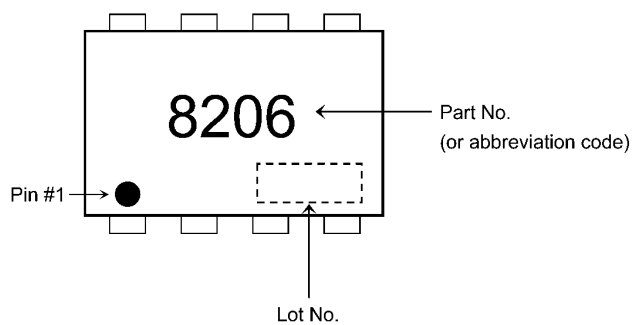
6.3. Gate Charge Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 16\text{ V}, V_{GS} = 5\text{ V}, I_D = 6.0\text{ A}$	—	5.8	—	nC
Gate-source charge 1	Q_{gs1}		—	1.3	—	
Gate-drain charge	Q_{gd}		—	1.1	—	

6.4. Source-Drain Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Reverse drain current (pulsed) (Note 7)	I_{DRP}	—	—	—	20	A
Diode forward voltage	V_{DSF}	$I_{DR} = 6.0\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.2	V

Note 7: Ensure that the channel temperature does not exceed 150°C .

7. Marking**Fig. 7.1 Marking**

8. Characteristics Curves (Note)

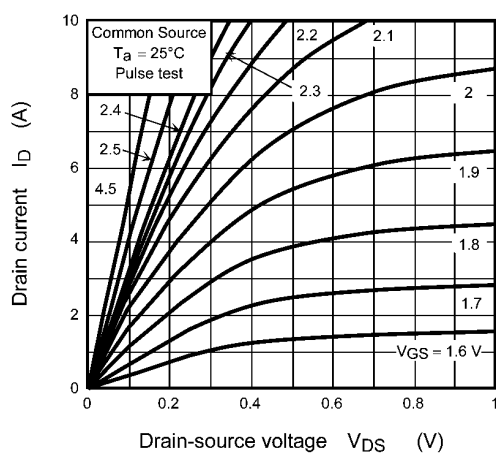


Fig. 8.1 $I_D - V_{DS}$

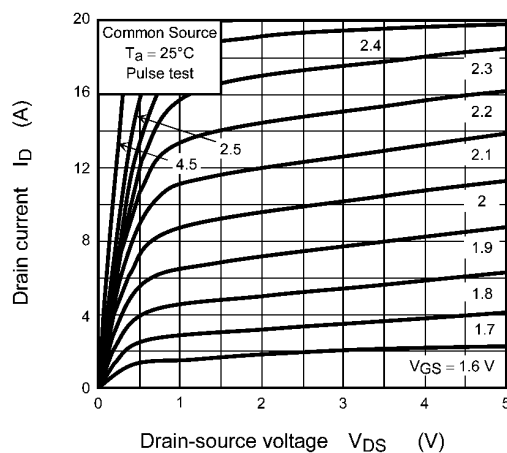


Fig. 8.2 $I_D - V_{DS}$

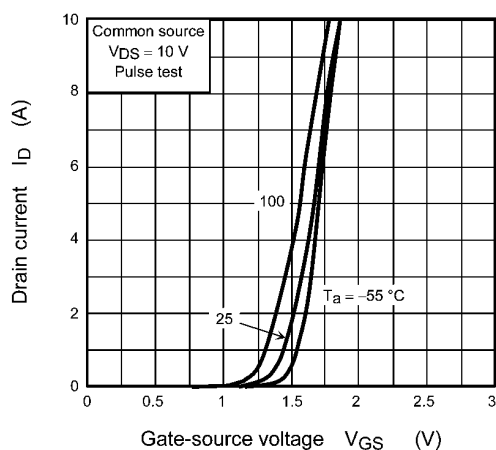


Fig. 8.3 $I_D - V_{GS}$

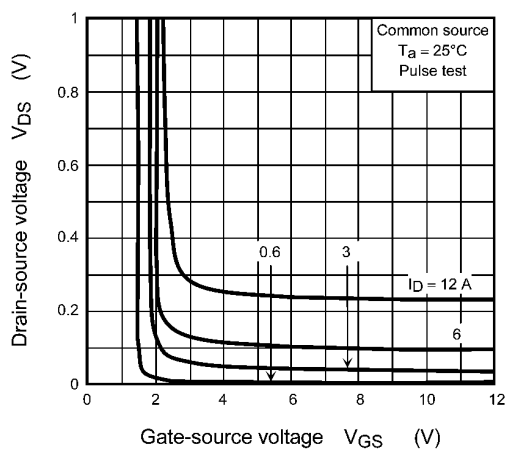


Fig. 8.4 $V_{DS} - V_{GS}$

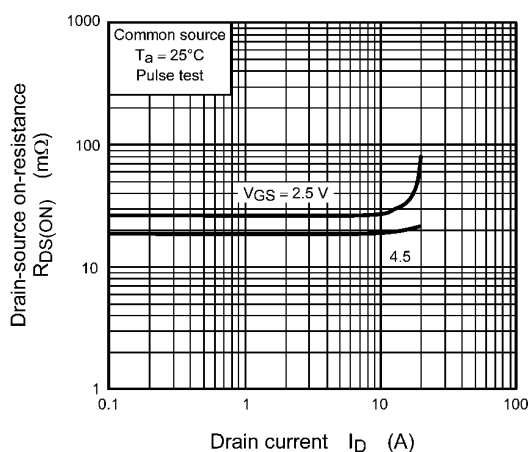


Fig. 8.5 $R_{DS(ON)} - I_D$

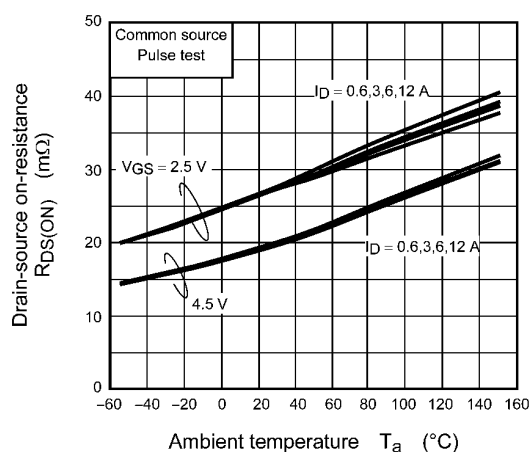


Fig. 8.6 $R_{DS(ON)} - T_a$

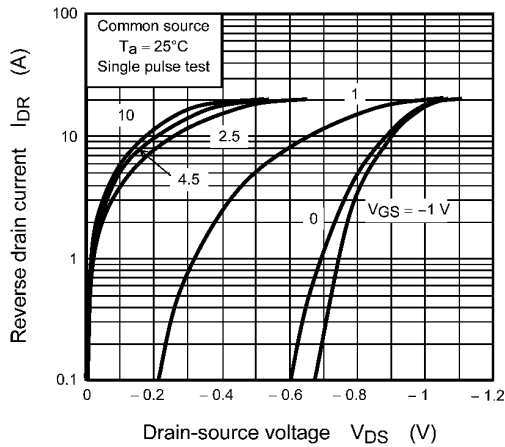


Fig. 8.7 $I_{DR} - V_{DS}$

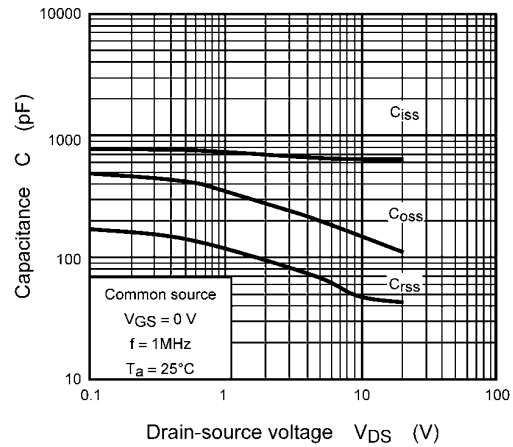


Fig. 8.8 Capacitance - V_{DS}

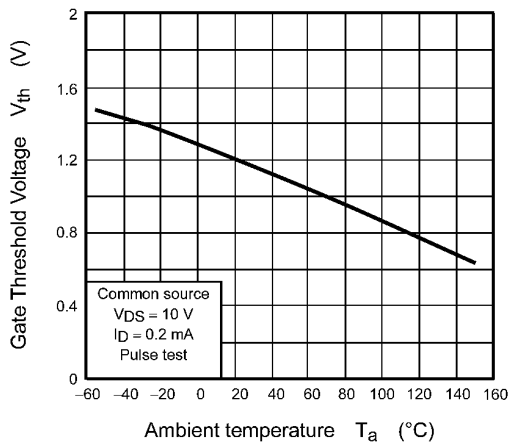


Fig. 8.9 $V_{th} - T_a$

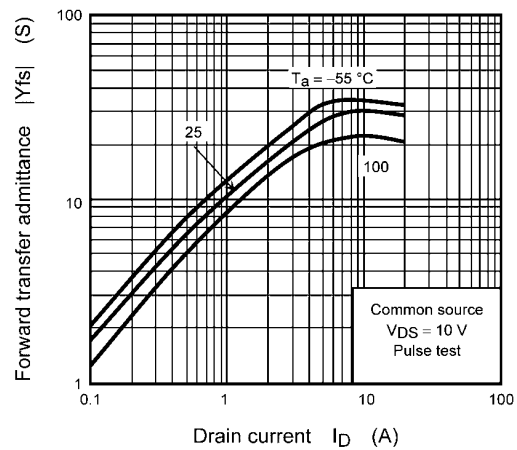


Fig. 8.10 $|Y_{fs}| - I_D$

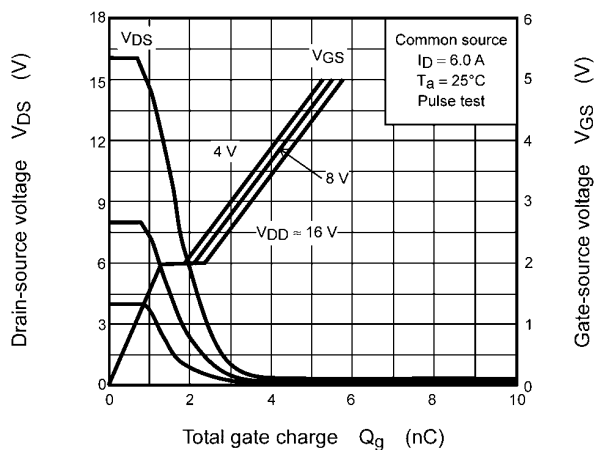
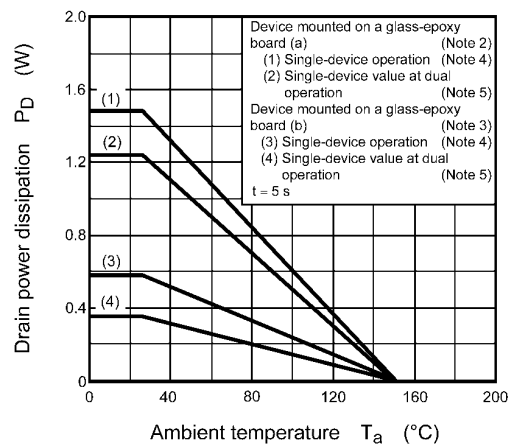


Fig. 8.11 Dynamic Input/Output Characteristics



**Fig. 8.12 $P_D - T_a$
(Guaranteed Maximum)**

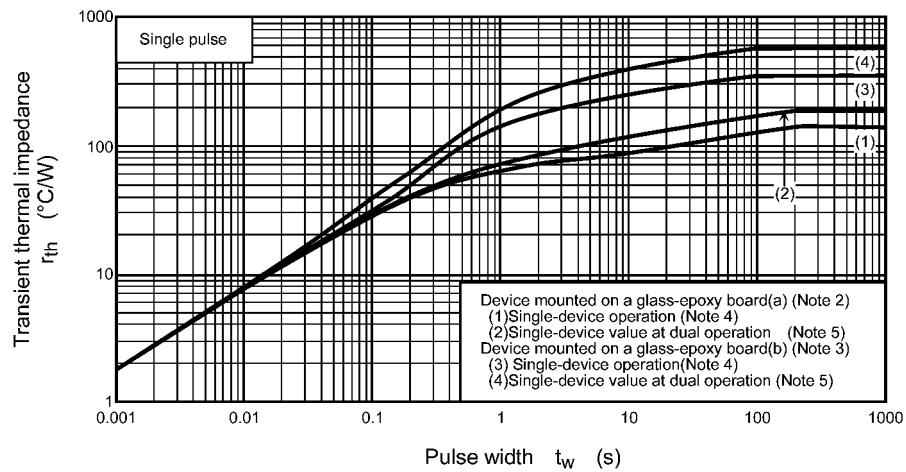


Fig. 8.13 $r_{th} - t_w$
(Guaranteed Maximum)

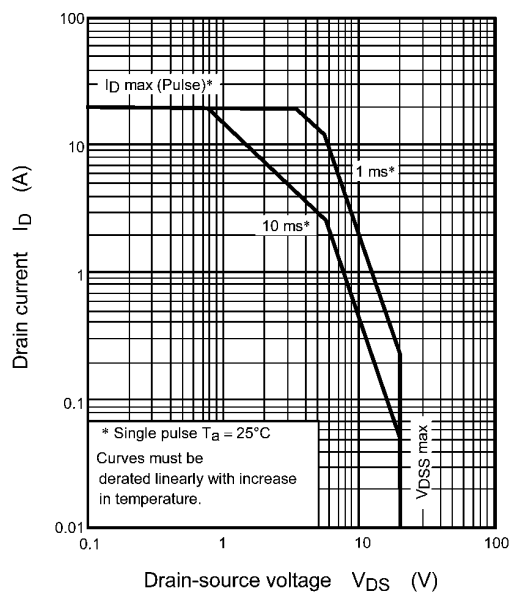
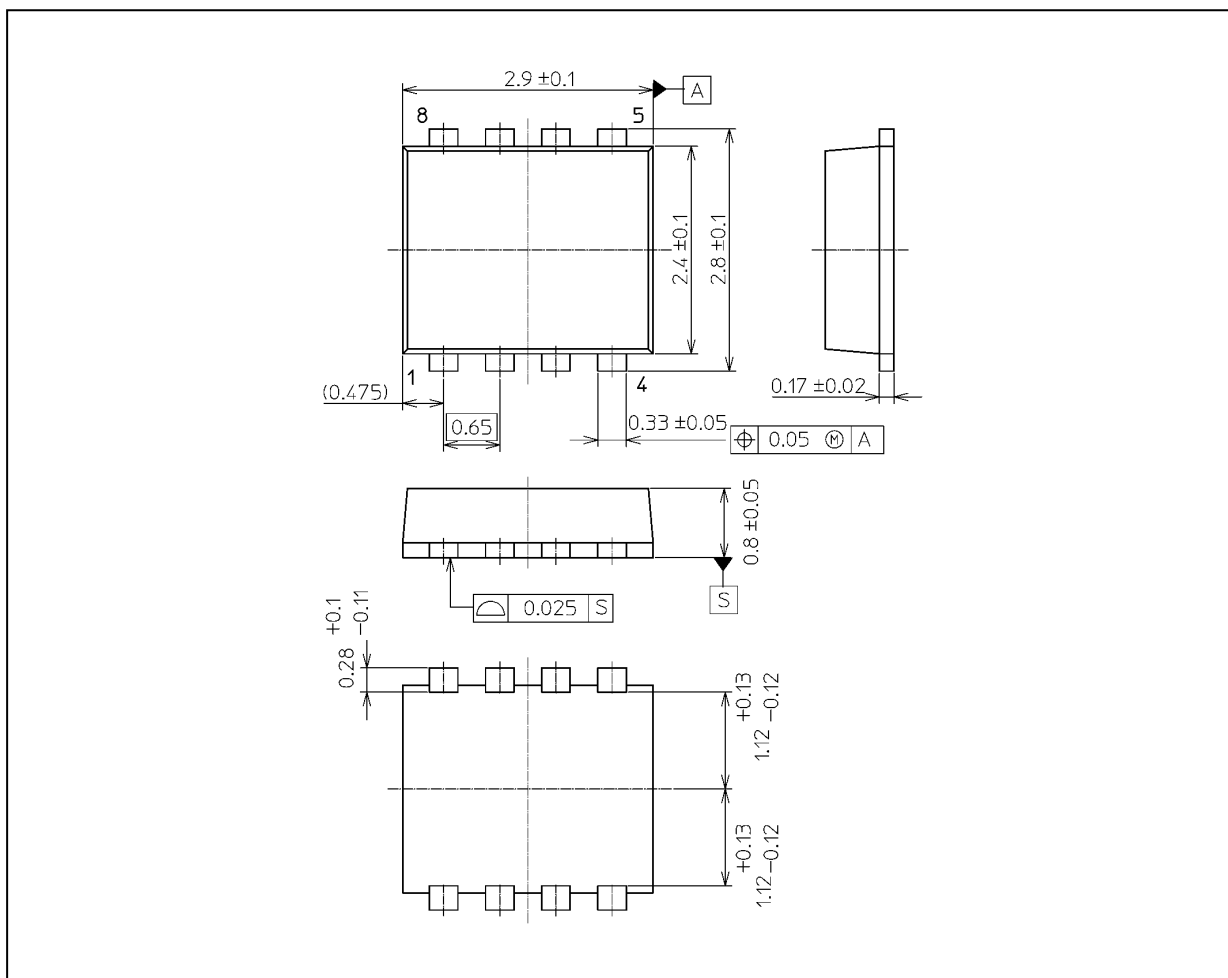


Fig. 8.14 Safe Operating Area
(Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.017 g (typ.)

Package Name(s)
TOSHIBA: 2-3V1S
Nickname: PS-8

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